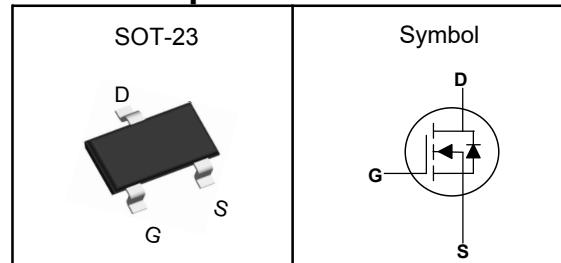


N-Channel Enhancement Mode MOSFET

Features

- Fast switching speed
- Reliable and Rugged
- ROHS Compliant
- 100% UIS and Rg Tested

Pin Description



Applications

- Power Management in Desktop Computer
- DC/DC Converters

V_{DSS}	40	V
$R_{DS(ON)-Typ}$	32	$\text{m}\Omega$
I_D	4	A

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
V_{DSS}	Drain-Source Voltage	40	V
V_{GSS}	Gate-Source Voltage	± 20	V
T_J	Maximum Junction Temperature	-55 to 150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$I_{DM}^{①}$	Pulse Drain Current Tested	16	A
I_D	Continuous Drain Current	4	A
P_D	Maximum Power Dissipation	1.04	W

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	104	$^\circ\text{C}/\text{W}$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C .

Note ③ : Surface Mounted on 1in² FR-4 board with 1oz.



N-Channel Enhancement Mode MOSFET

Electrical Characteristics ($T_J=25^\circ\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	40	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=40\text{V}$, $V_{\text{GS}}=0\text{V}$	---	---	1	μA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_D=250\mu\text{A}$	1.0	---	3.0	V
I_{GSS}	Gate Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
$R_{\text{DS(ON)}}$	Drain-Source On-state Resistance	$V_{\text{GS}}=10\text{V}$, $I_D=4\text{A}$	---	32	40	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_D=3.5\text{A}$	---	50	65	$\text{m}\Omega$
Dynamic Characteristics^⑤						
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=20\text{V}$, Freq.=1MHz	---	558	---	pF
C_{oss}	Output Capacitance		---	70	---	
C_{rss}	Reverse Transfer Capacitance		---	30	---	
$T_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DS}}=20\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=1\Omega$	---	12	---	nS
T_r	Turn-on Rise Time		---	49	---	
$T_{\text{d(off)}}$	Turn-off Delay Time		---	37	---	
T_f	Turn-off Fall Time		---	10	---	
g_{fs}	Forward Transconductance	$V_{\text{DS}}=15\text{V}$, $I_D=2\text{A}$	---	---	---	S
Q_g	Total Gate Charge	$V_{\text{DS}}=20\text{V}$, $V_{\text{GS}}=10\text{V}$, Freq.=1MHz	---	10	---	nC
Q_{gs}	Gate-Source Charge		---	1.4	---	
Q_{gd}	Gate-Drain Charge		---	1.9	---	
Source-Drain Characteristics ($T_J=25^\circ\text{C}$)						
V_{SD}	Diode Forward Voltage ₂	$V_{\text{GS}}=0\text{V}$, $I_S=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1.2	V

Note ④ : Pulse test (pulse width≤300us, duty cycle≤2%).

Note ⑤ : Guaranteed by design, not subject to production testing.

N-Channel Enhancement Mode MOSFET

Typical Characteristics

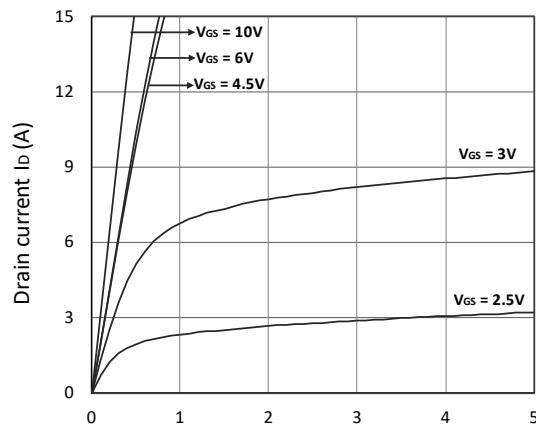


Figure 1. Output Characteristics

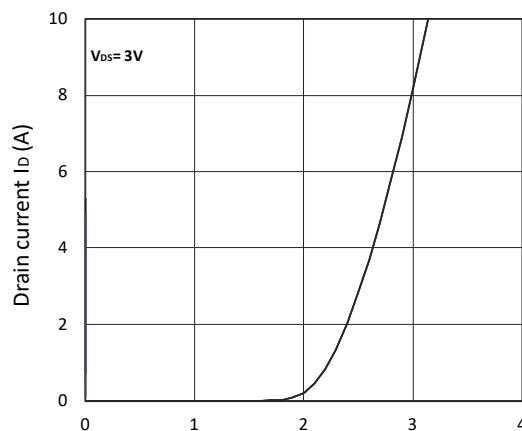


Figure 2. Transfer Characteristics

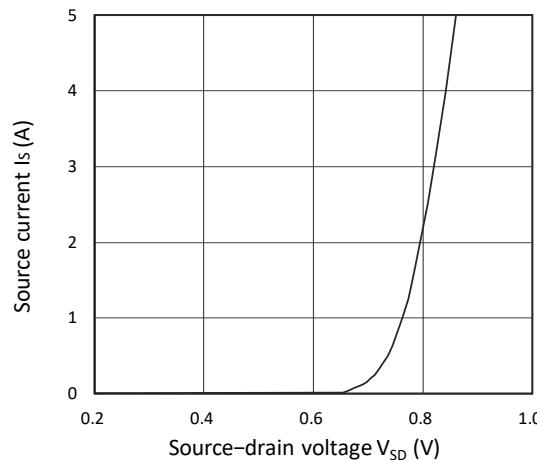


Figure 3. Forward Characteristics of Reverse

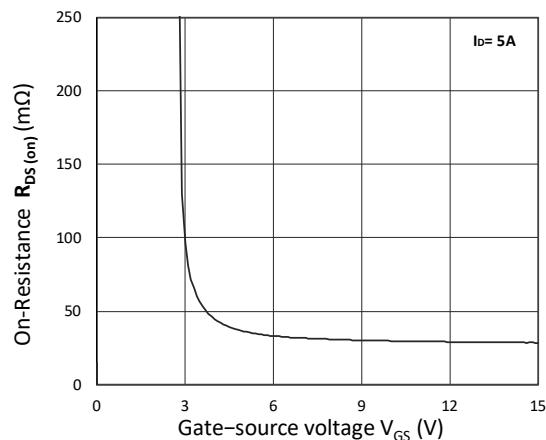


Figure 4. $R_{DS(on)}$ vs. V_{GS}

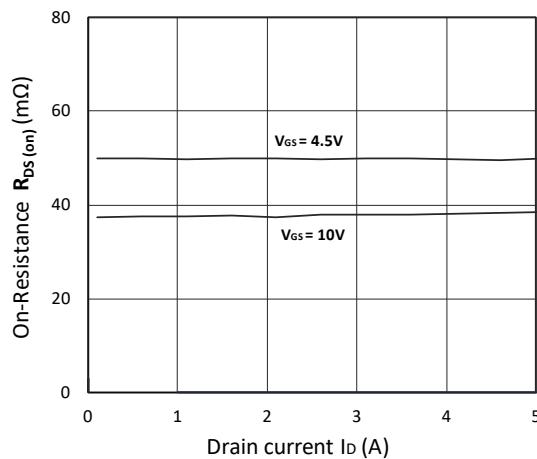


Figure 5. $R_{DS(on)}$ vs. I_D

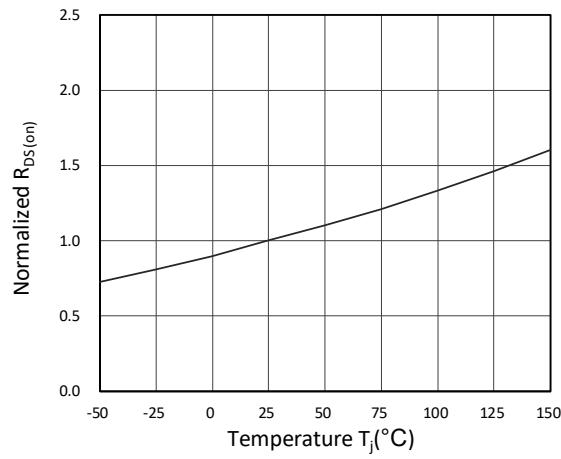


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature

N-Channel Enhancement Mode MOSFET

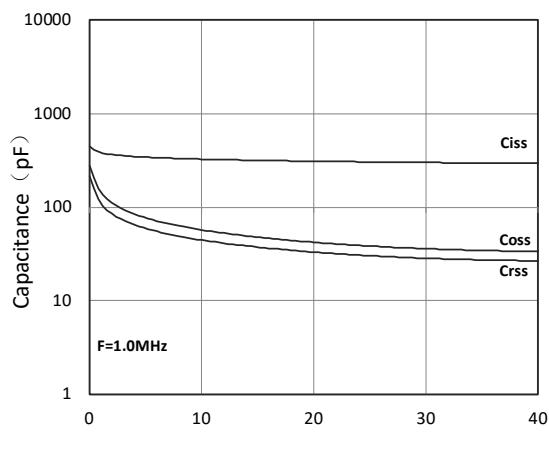


Figure 7. Capacitance Characteristics

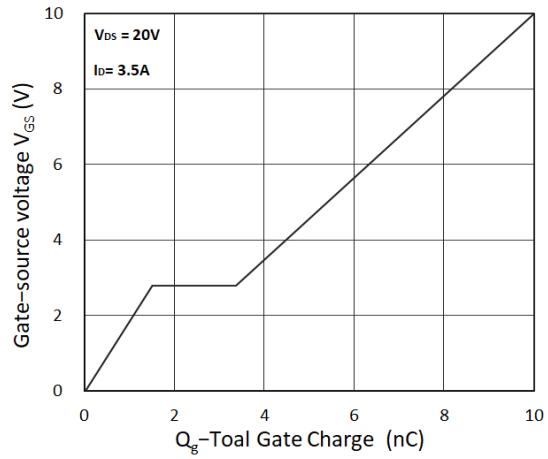
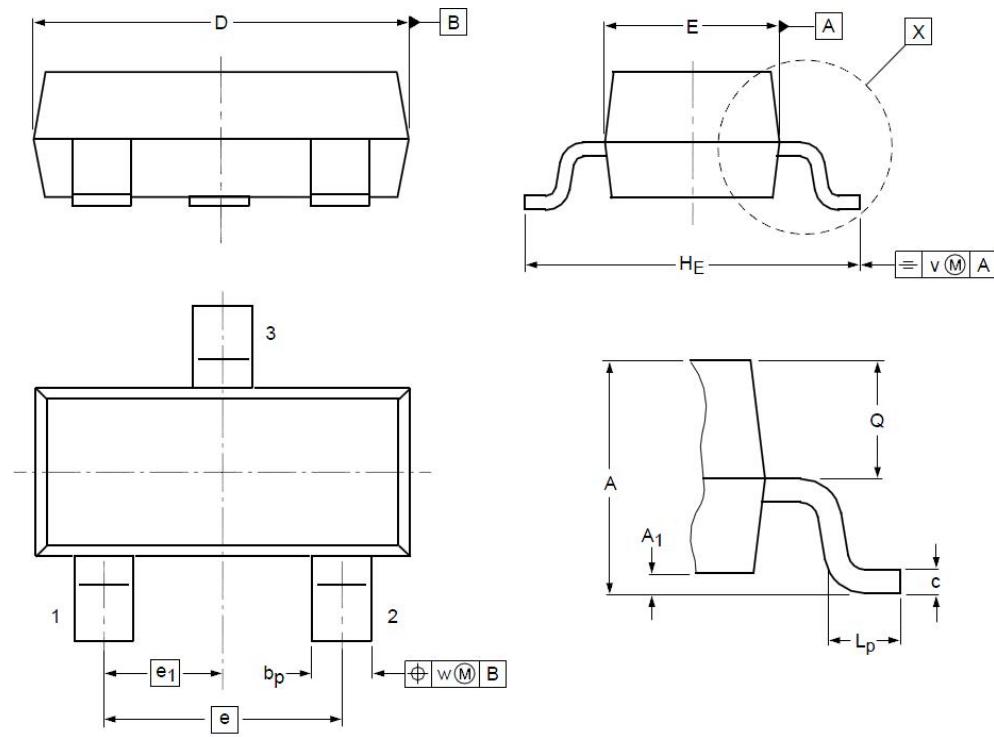


Figure 8. Gate Charge Characteristics

N-Channel Enhancement Mode MOSFET

SOT23 Package Outline Dimensions



Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	0.90	1.05	1.20	e₁	--	0.95	--
A₁	0.01	0.05	0.10	H_E	2.10	2.40	2.50
b_p	0.38	0.42	0.48	L_p	0.40	0.50	0.60
c	0.09	0.13	0.15	Q	0.45	0.49	0.55
D	2.80	2.92	3.00	V	--	0.20	--
E	1.20	1.33	1.40	W	--	0.10	--
e	--	1.90	--				